

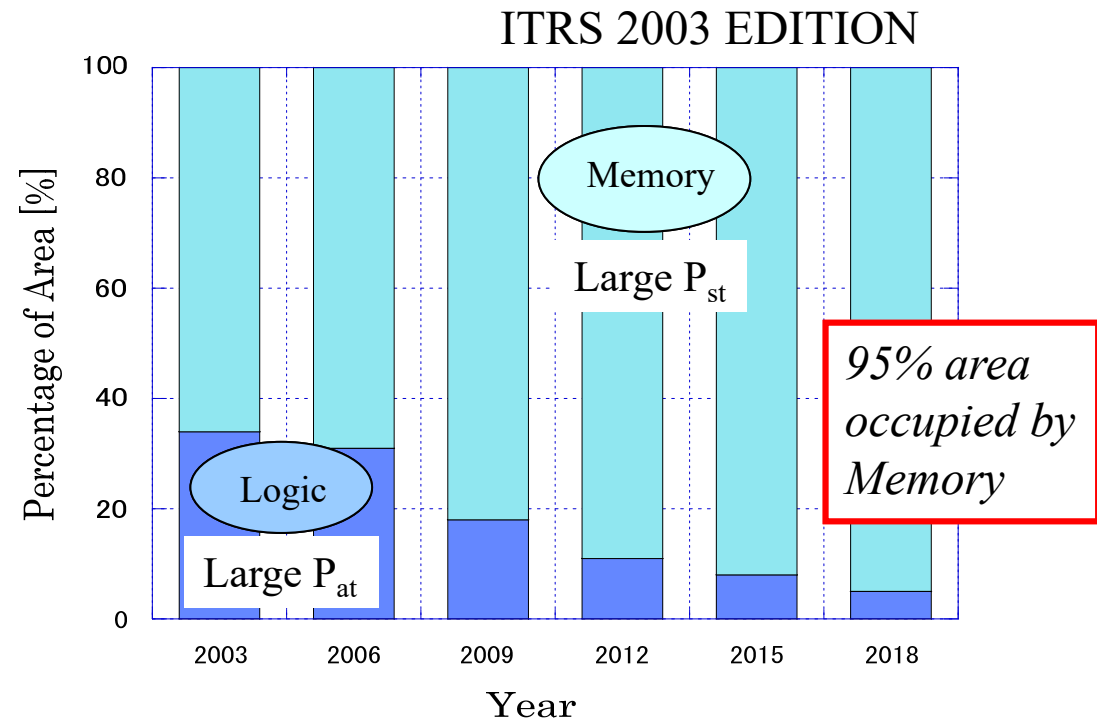
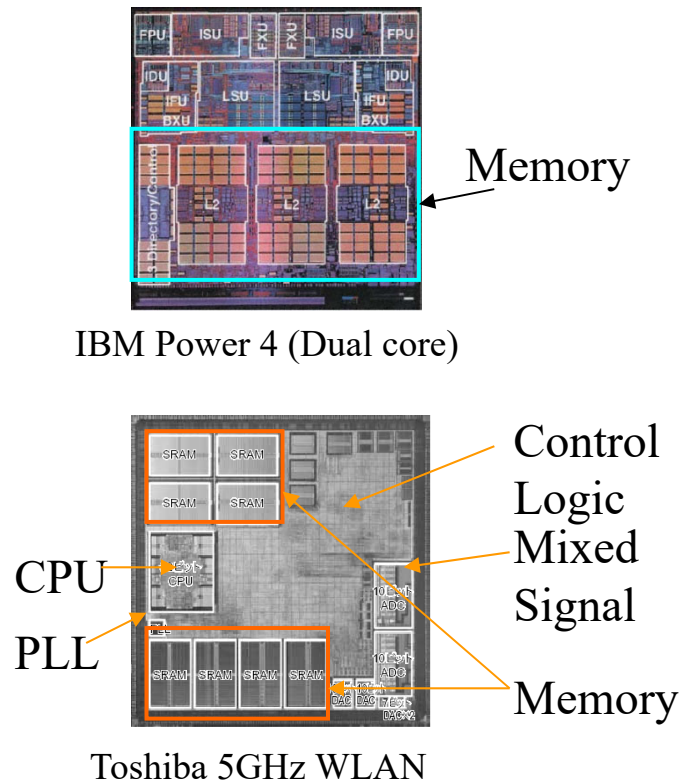
6.2 Power consumption

Analysis of power consumption and
clock frequency

Power consumption in CMOS logic

- Classification of current path
- a. $P_{cd}(W)$ by a charge-discharge current
 - b. $P_{dp}(W)$ by a direct path short circuit current
 - c. $P_L(W)$ by a subthreshold current, pn junction leakage current, gate tunneling current
- Classification of operating mode
- a. Dynamic power consumption $P_{at}(W)$
 - b. Static power consumption $P_{st}(W)$

Trends of power consumption



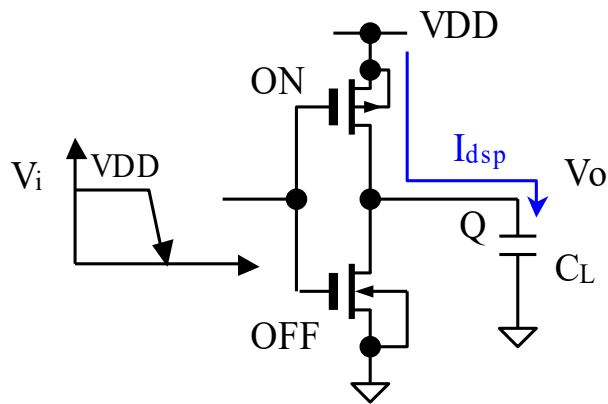
The static power consumption by memory is increasing with the generation.

Charge-discharge current (Charge)

Charge current and output voltage

$$Q = C_L \cdot V_O$$

$$I_{dsp} = \frac{dQ}{dt} = C_L \cdot \frac{dV_O}{dt}$$



Energy consumption by p-ch MOSFET

$$\begin{aligned} E_C &= \int_0^{\infty} I_{dsp}(t) \{VDD - V_O(t)\} dt \\ &= VDD \int_0^{\infty} I_{dsp}(t) dt - \int_0^{\infty} I_{dsp}(t) \cdot V_O(t) dt \\ &= VDD \int_0^{VDD} C_L dV_O - \int_0^{VDD} C_L \cdot V_O dV_O \\ &= \frac{C_L}{2} VDD^2 \end{aligned}$$

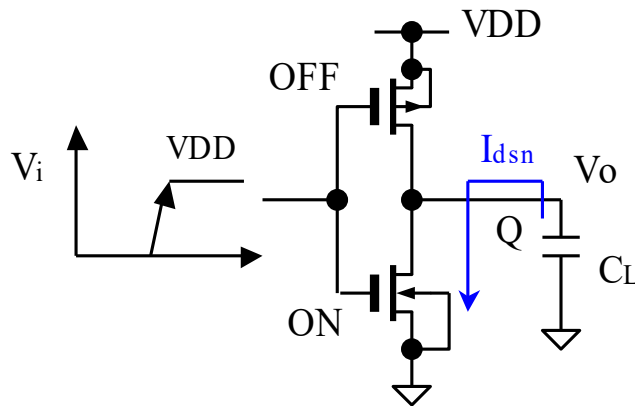
[Note] The total supply energy is $C_L VDD^2$. The half of them is dissipated from p-ch MOSFET and The half of them is storied in C_L .

Charge-discharge current (Discharge)

Discharge current and output voltage

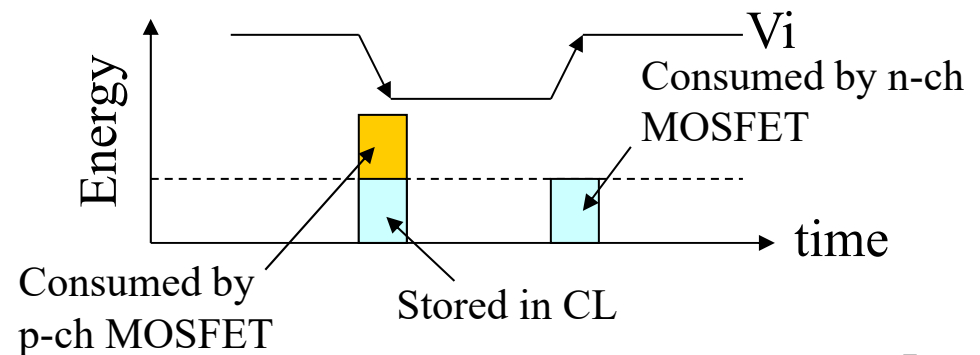
$$Q = C_L \cdot V_O$$

$$I_{dsn} = -\frac{dQ}{dt} = -C_L \cdot \frac{dV_O}{dt}$$



Energy consumption by n-ch MOSFET

$$\begin{aligned} E_d &= \int_0^\infty I_{dsn}(t) \cdot V_O(t) dt \\ &= \int_{VDD}^0 (-C_L \cdot V_O) dV_O \\ &= \frac{C_L}{2} VDD^2 \end{aligned}$$



Power consumption by charge-discharge current

Energy consumption of an inverter for a clock cycle

$$\begin{aligned} E_{cyc} &= E_c + E_d \\ &= C_L \cdot VDD^2 \quad (\text{J}) \end{aligned}$$

An average power consumption P_{cd} for a clock cycle

$$P_{cd} = E_{cyc} / T_C$$

$$= C_L \cdot f_C \cdot VDD^2$$

Important!

2 transitions per 1 cycle

Clock
frequency

Power
supply
voltage

Parameters to reduce
the power consumption

Switching activity of a logic gate

D # r z h u # r q v x p s w r q # r i # d h v # g h s h q g v # r q # k h # u d q v l w r q # s u r e d e l w | #
 e h w z h h q # k h # r j l f # y d o x h 1

Example of 2-input NAND

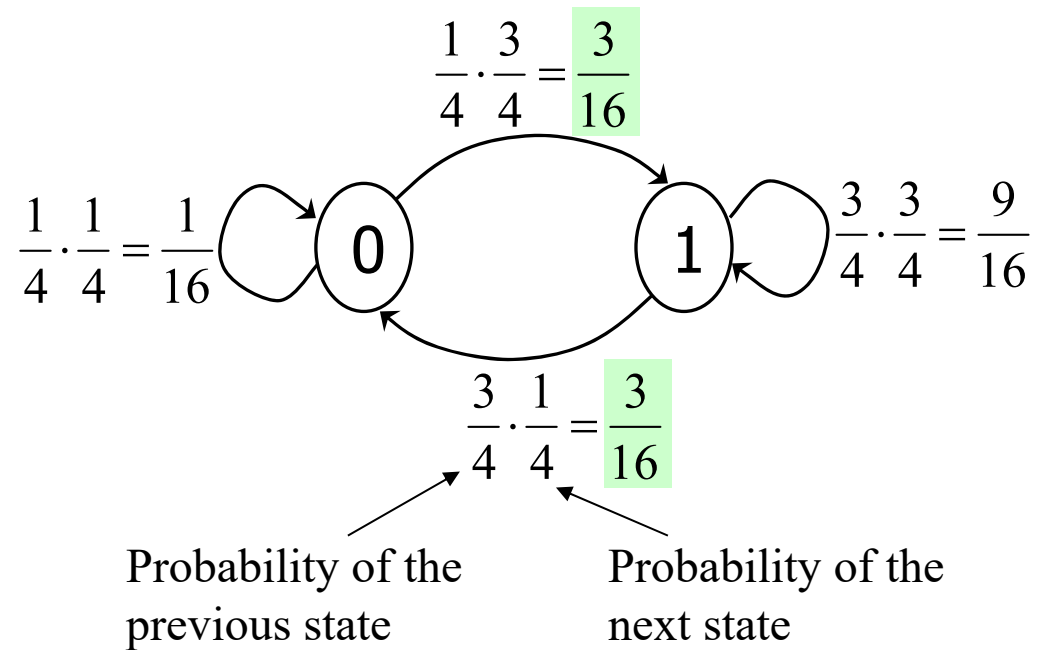
A	B	Z
0	0	1
0	1	1
1	0	1
1	1	0

} Probability 3/4
 } Probability 1/4

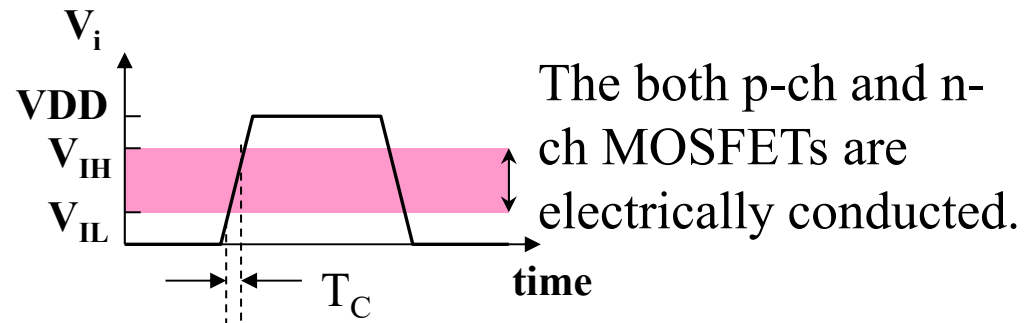
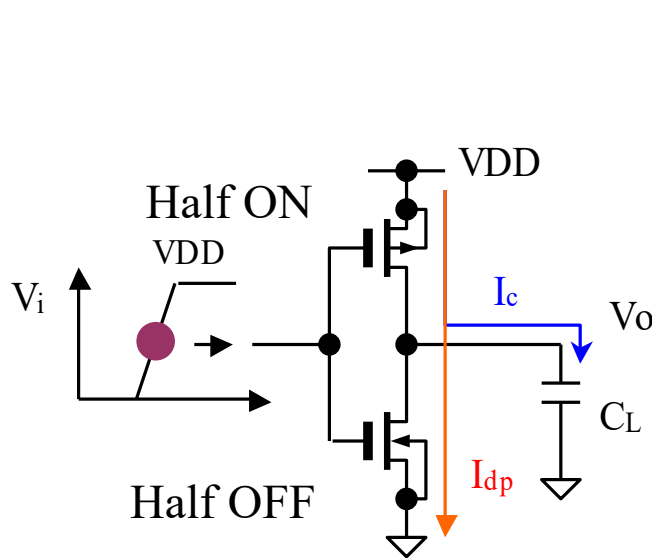
$$P_{cd} = C_L \cdot VDD^2 \cdot \frac{6}{16} f_C$$

Energy consumption for 1 cycle

Transition probability $P_{0 \leftrightarrow 1} = 6/16$



Direct path short circuit current

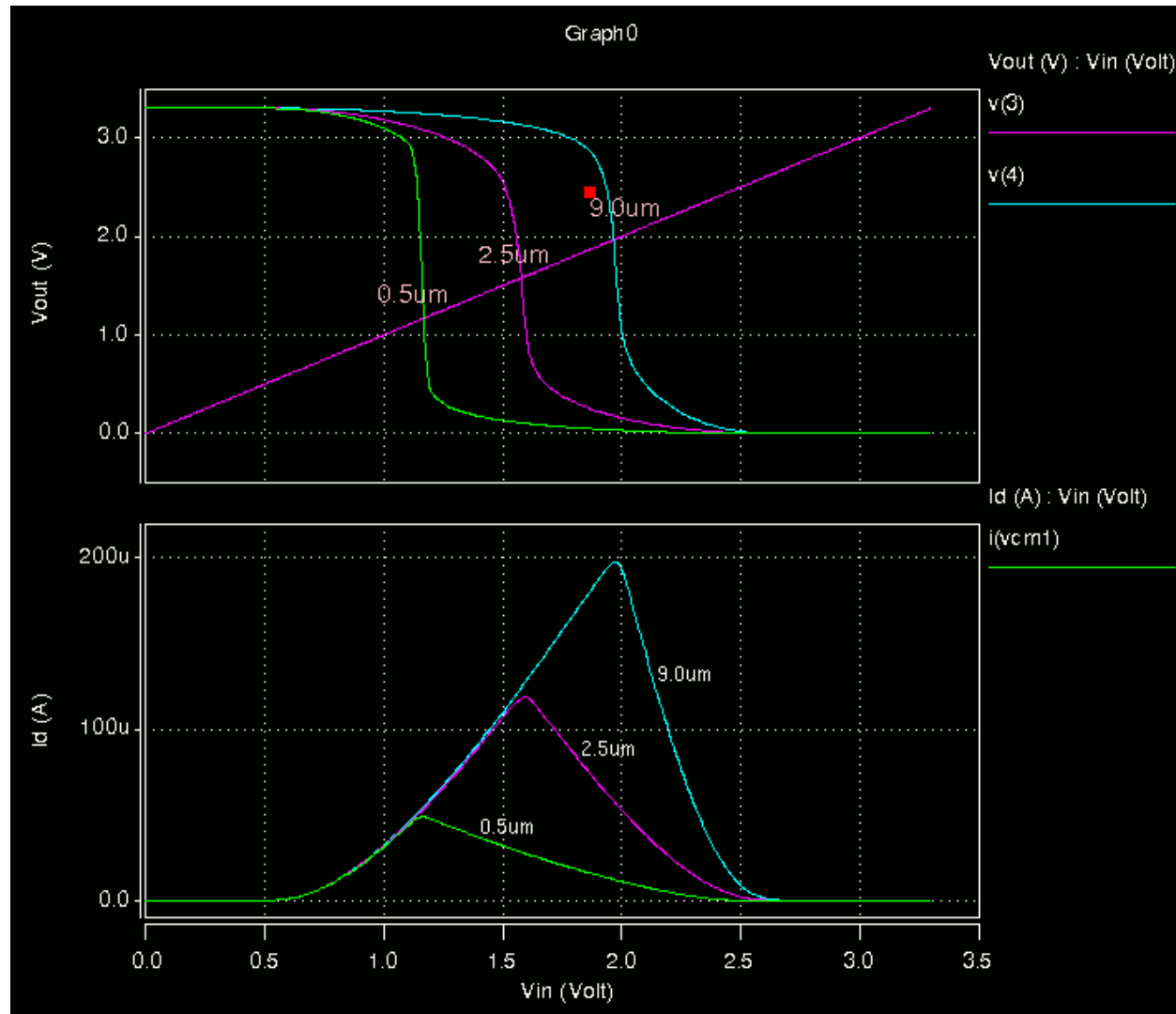


$$P_{dp} = VDD \cdot f_C \cdot 2 \int_0^{T_C} I_{dp}(t) \cdot dt$$

$$\cong 2 \cdot VDD \cdot f_C \cdot \overline{I_{dp}} \cdot T_C$$

1. The current in p-ch MOSFET is branched to the short circuit current I_{dp} and the charge-discharge current I_c . If the current I_c is large enough, the current I_{dp} is ignored.
2. The short rise time and fall time of input signal are effective to reduce the current P_{dp} .

Maximum direct path short circuit current

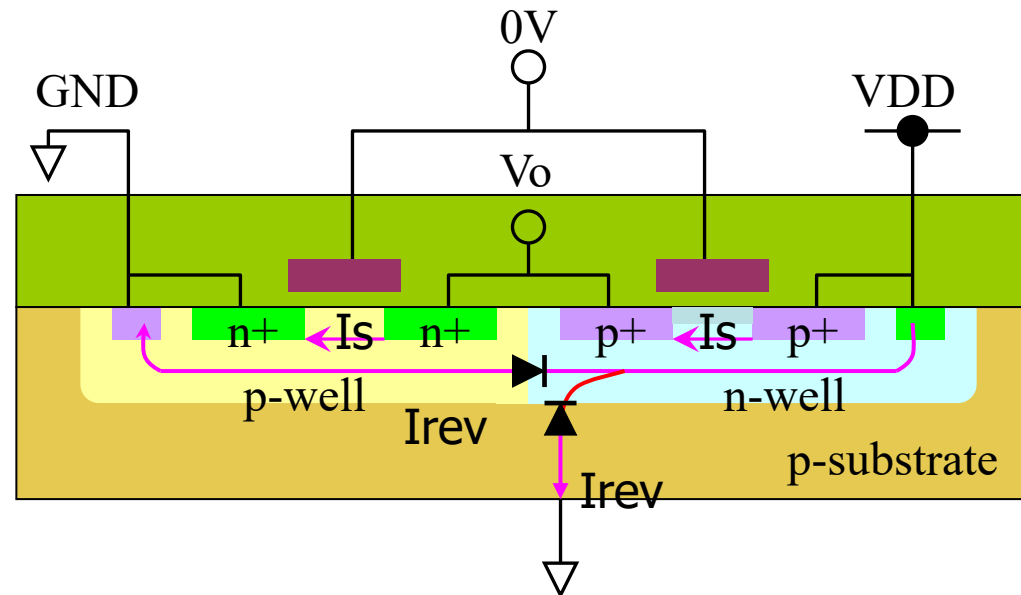


DC transfer characteristics. $W_n = \text{const.}$ and W_p is a parameter.

The maximum current and gate threshold depend on W_n and W_p , respectively.

Leakage currents

A leakage currents is increasing with shrinking the MOSFET size.



- Reverse current of pn junctions I_{rev}
- Subthreshold current of MOSFET I_S
- Gate tunneling current I_T

The leakage current increases with shrinking the size of MOSFETs.

$$\begin{aligned}
 P_l &= VDD \cdot I_{leak} \\
 &= VDD \cdot (I_{rev} + I_S + I_T)
 \end{aligned}$$

Estimation of power consumption

The total power consumption P_{total} is the sum of the dynamic power consumption P_{at} and the static power consumption P_{st} . The power consumption by the direct path short circuit current can be typically ignored.

$$P_{total} = P_{at} + P_{st}$$

$$\left\{ \begin{array}{l} P_{at} \cong \kappa \cdot N_g \cdot P_{cd} = \kappa \cdot N_g \cdot f_c \cdot C_L \cdot VDD^2 \\ P_{st} \cong N_g \cdot P_l = N_g \cdot I_l \cdot VDD \end{array} \right.$$

N_g Number of gates

κ Activity factor of gates

C_L Load capacitance per gate

f_c Clock frequency

$$f_{max} = \frac{VDD}{3.70C_L} \frac{\beta_n \beta_p}{\beta_n + \beta_p}$$

P_{cd} Power consumption by the charge-discharge current in a gate

P_l Power consumption by the average leakage current in a gate

k Transition probability of gate in a clock cycle

Low power design 1

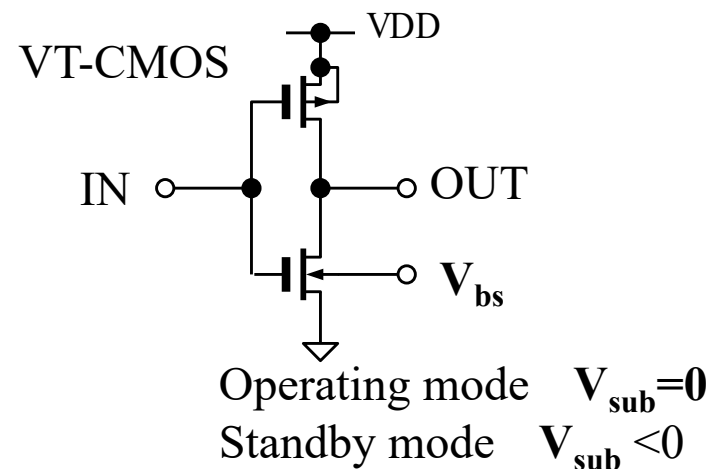
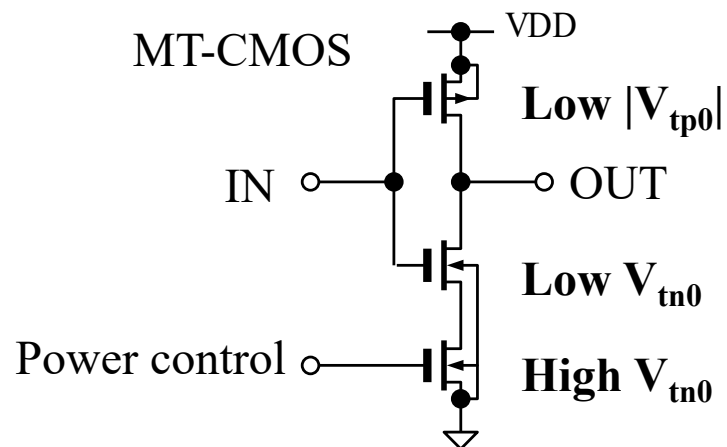
Reduction of P_{at}

- Reducing the supply voltage V_{DD}
- Reducing the clock frequency
- Clock gating for the circuit block in standby mode
- Reducing the operation amount (by the improvement of the algorithm)
- Implementation by asynchronous circuit without a clock signal
- Implementation by adiabatic logic circuit

Low power design 2

Reduction of P_{st}

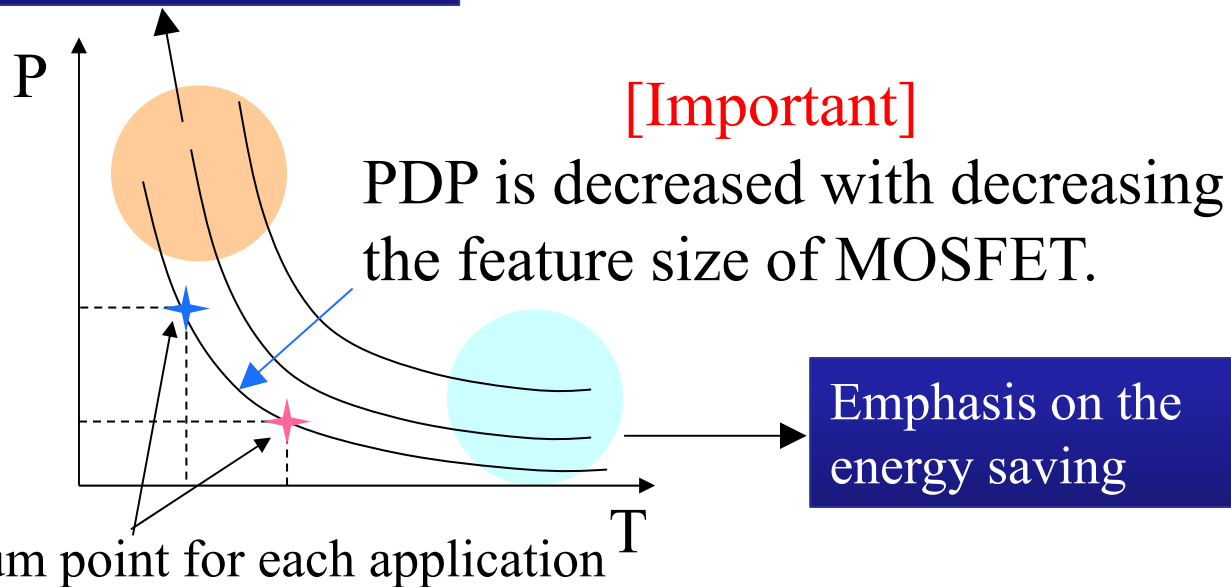
- Reducing the supply voltage VDD
- Controlling the threshold voltage of MOSFET
 - MTCMOS (Multi-threshold CMOS)
 - Power gating by the high threshold MOSFET
 - VTCMOS (Variable threshold CMOS)
 - Leakage current reduction by controlling V_{bs}
 - Nonvolatile memory and power gating



Power-delay product (PDP)

$$\begin{aligned} \text{For an inverter, } PDP &= P_{at} \cdot t_d = C_L f_c VDD^2 \frac{1}{f_c} \\ &= C_L VDD^2 \leftarrow \text{Depends on the fabrication} \\ &\quad \text{technology} \end{aligned}$$

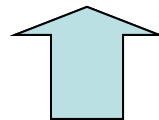
Emphasis on the
operating speed



Packaging and power consumption

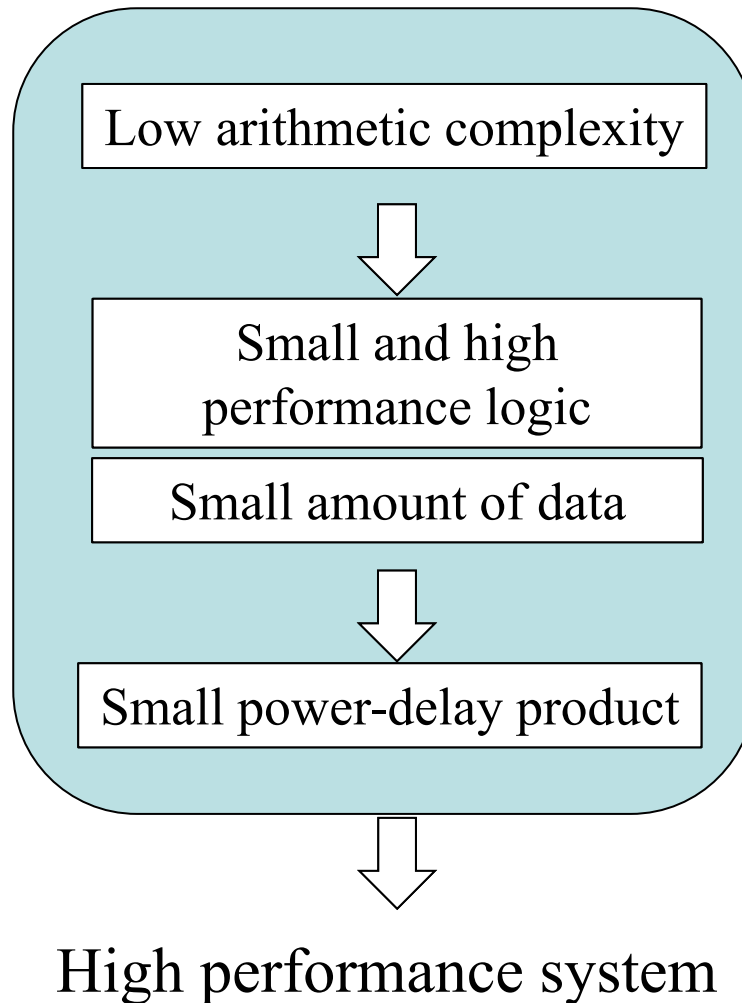
Allowable power loss

{	Ceramic package	10W	High speed
	Plastic molding	1W	↑
	Mobile applications	0.1~0.01W	↓
	Energy harvesting	0.001W	Low power



Minimum clock frequency and Minimum power supply
by the optimization of the operating point on PDP curve.

System optimization of digital LSI



← Evaluation in algorithm design

← Evaluation in logic design

← Evaluation in logic design

← Technology options to optimize the PDP

[Note] A top-down design method with CAD software and emulator is effective to optimize the whole system.